



**100V 9.4mΩ N-Ch Power MOSFET**

**Features**

- Ultra-low  $R_{DS(ON)}$
- Low Gate Charge
- 100% UIS Tested, 100%  $R_g$  Tested
- Pb-free Lead Plating
- Halogen-free and RoHS-compliant

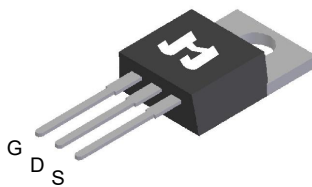
**Product Summary**

Parameter	Typ.	Unit
$V_{DS}$	100	V
$V_{GS(th)}$	2.7	V
$I_D$ (@ $V_{GS} = 10V$ ) <sup>(1)</sup>	65	A
$R_{DS(ON)}$ (@ $V_{GS} = 10V$ )	9.4	mΩ

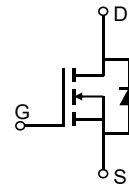
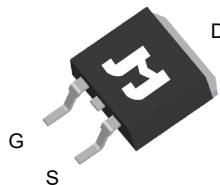
**Applications**

- Power Management in Telecom., Industrial Automation, CE
- Motor Driving in Power Tool, E-vehicle, Robotics
- Current Switching in DC/DC & AC/DC (SR) Sub-systems

TO-220-3L Top View



TO-263-3L Top View

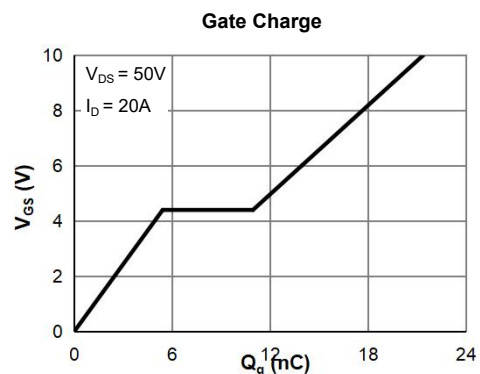
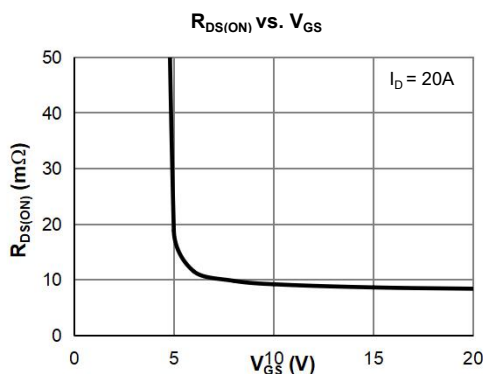


**Ordering Information**

Device	Package	# of Pins	Marking	MSL	$T_J$ (°C)	Media	Quantity (pcs)
JMSH1010AC-U	TO-220-3L	3	SH1010A	N/A	-55 to 150	Tube	50
JMSH1010AE-13	TO-263-3L	3	SH1010A	3	-55 to 150	13-inch Reel	800

**Absolute Maximum Ratings** (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DS}$	100	V
Gate-to-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current <sup>(1)</sup>	$I_D$	$T_C = 25^\circ\text{C}$	65
		$T_C = 100^\circ\text{C}$	41
Pulsed Drain Current <sup>(2)</sup>	$I_{DM}$	176	A
Avalanche Current <sup>(3)</sup>	$I_{AS}$	37	A
Avalanche Energy <sup>(3)</sup>	$E_{AS}$	68	mJ
Power Dissipation <sup>(4)</sup>	$P_D$	$T_C = 25^\circ\text{C}$	96
		$T_C = 100^\circ\text{C}$	38
Junction & Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C





**Electrical Characteristics** (@  $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$ $T_J = 55^\circ\text{C}$			1.0 5.0	$\mu\text{A}$
Gate-Body Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	2.7	4.0	V
Static Drain-Source ON-Resistance	$R_{DS(ON)}$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$		9.4	11.8	$\text{m}\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = 5\text{V}, I_D = 20\text{A}$		47		S
Diode Forward Voltage	$V_{SD}$	$I_S = 1\text{A}, V_{GS} = 0\text{V}$		0.70	1.0	V
Diode Continuous Current	$I_S$	$T_C = 25^\circ\text{C}$			96	A

**DYNAMIC PARAMETERS** <sup>(5)</sup>

Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V}, f = 1\text{MHz}$		1372		pF
Output Capacitance	$C_{oss}$			291		pF
Reverse Transfer Capacitance	$C_{rss}$			6.2		pF
Gate Resistance	$R_g$	$V_{GS} = 0\text{V}, V_{DS} = 0\text{V}, f = 1\text{MHz}$		2.0		$\Omega$

**SWITCHING PARAMETERS** <sup>(5)</sup>

Total Gate Charge (@ $V_{GS} = 10\text{V}$ )	$Q_g$	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 50\text{V}, I_D = 20\text{A}$		21		nC
Total Gate Charge (@ $V_{GS} = 6.0\text{V}$ )	$Q_g$			13.9		nC
Gate Source Charge	$Q_{gs}$			5.4		nC
Gate Drain Charge	$Q_{gd}$			5.5		nC
Turn-On DelayTime	$t_{D(on)}$	$V_{GS} = 10\text{V}, V_{DS} = 50\text{V}$ $R_L = 2.5\Omega, R_{GEN} = 6\Omega$		10.7		ns
Turn-On Rise Time	$t_r$			20		ns
Turn-Off DelayTime	$t_{D(off)}$			25		ns
Turn-Off Fall Time	$t_f$			19.5		ns
Body Diode Reverse Recovery Time	$t_{rr}$		$I_F = 20\text{A}, dI_F/dt = 100\text{A}/\mu\text{S}$		48	
Body Diode Reverse Recovery Charge	$Q_{rr}$	$I_F = 20\text{A}, dI_F/dt = 100\text{A}/\mu\text{S}$		79		nC

**Thermal Performance**

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	52	63	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.0	1.3	$^\circ\text{C}/\text{W}$

**Notes:**

1. Computed continuous current assumes the condition of  $T_{J\_Max}$  while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under  $T_{J\_Max} = 150^\circ\text{C}$ .
3. This single-pulse measurement was taken under the following condition [ $L = 100\mu\text{H}, V_{GS} = 10\text{V}, V_{DS} = 50\text{V}$ ] while its value is limited by  $T_{J\_Max} = 150^\circ\text{C}$ .
4. The power dissipation  $P_D$  is based on  $T_{J\_Max} = 150^\circ\text{C}$ .
5. This value is guaranteed by design hence it is not included in the production test.

Typical Electrical & Thermal Characteristics

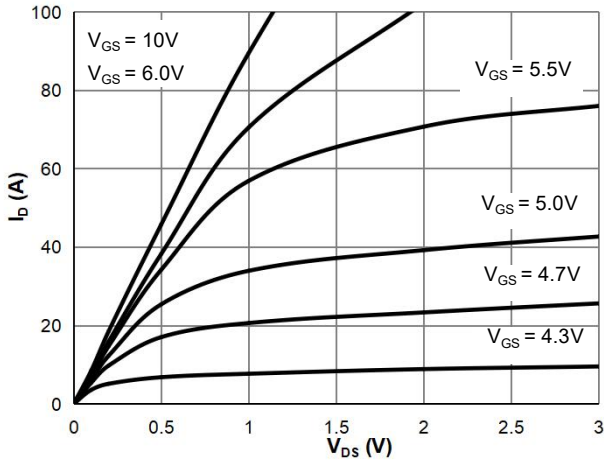


Figure 1: Saturation Characteristics

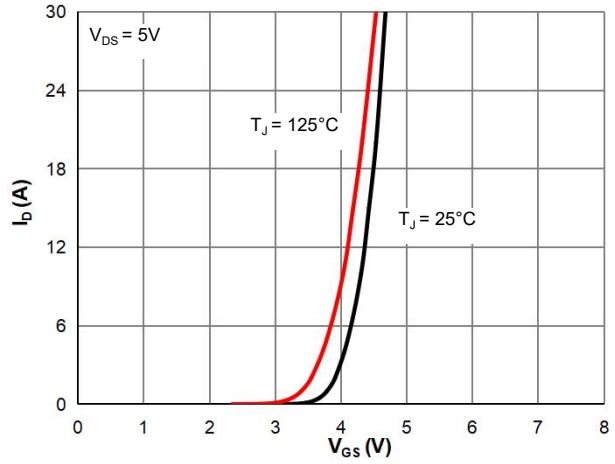


Figure 2: Transfer Characteristics

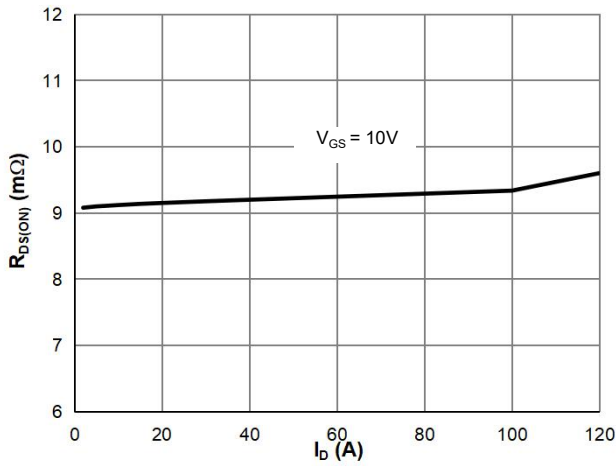


Figure 3:  $R_{DS(ON)}$  vs. Drain Current

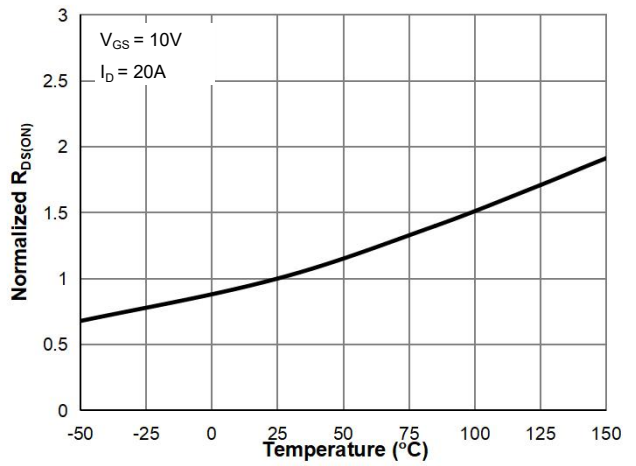


Figure 4:  $R_{DS(ON)}$  vs. Junction Temperature

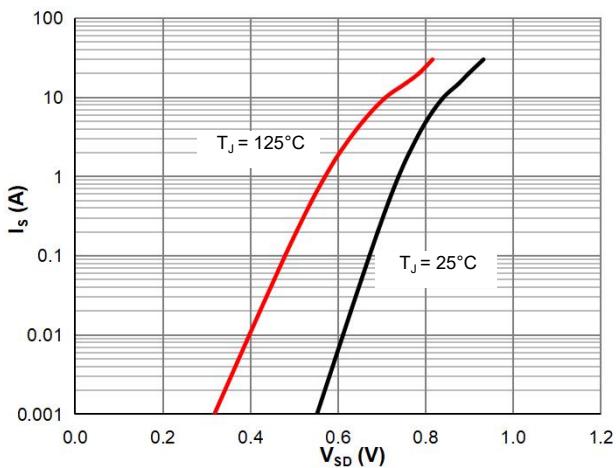


Figure 5: Body-Diode Characteristics

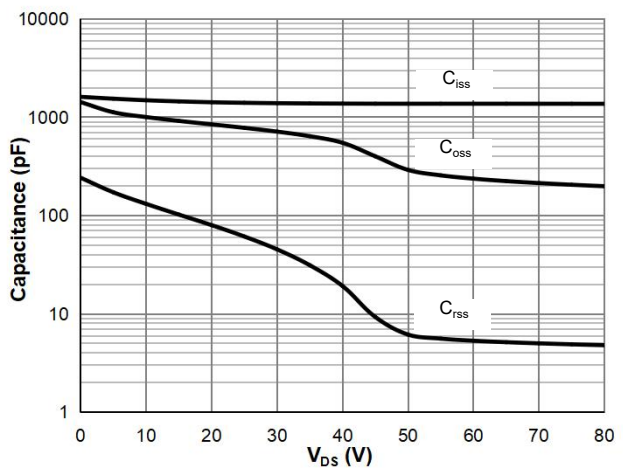


Figure 6: Capacitance Characteristics



Typical Electrical & Thermal Characteristics

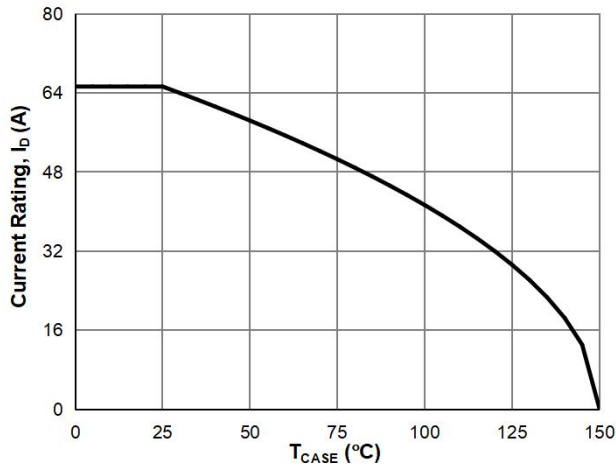


Figure 7: Current De-rating

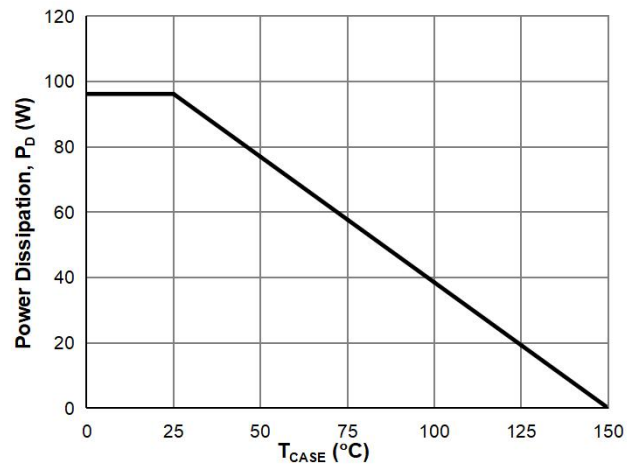


Figure 8: Power De-rating

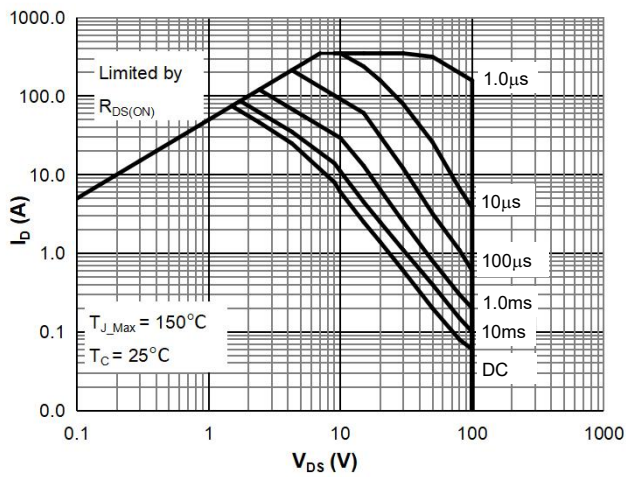


Figure 9: Maximum Safe Operating Area

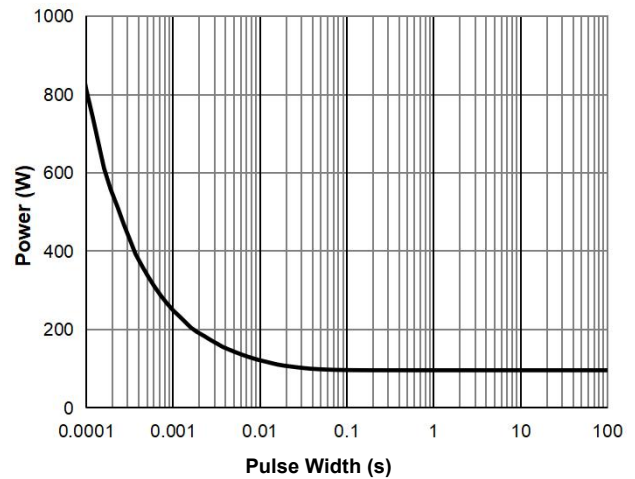


Figure 10: Single Pulse Power Rating, Junction-to-Case

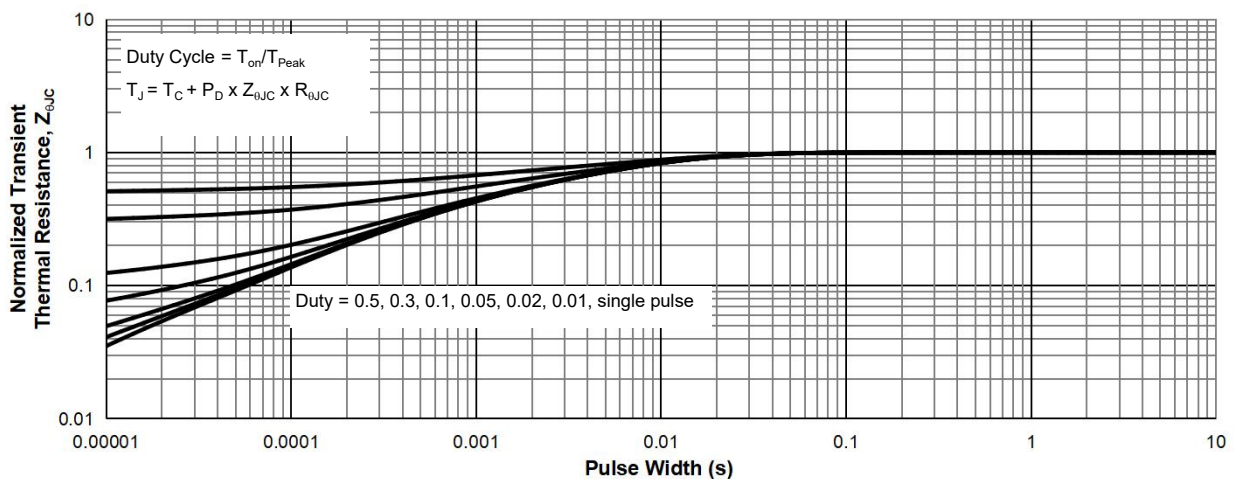
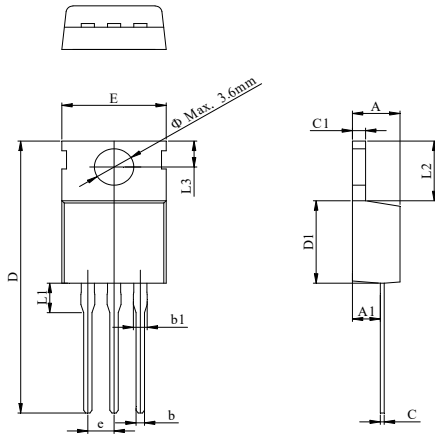


Figure 11: Normalized Maximum Transient Thermal Impedance

**TO-220-3L Package Information**

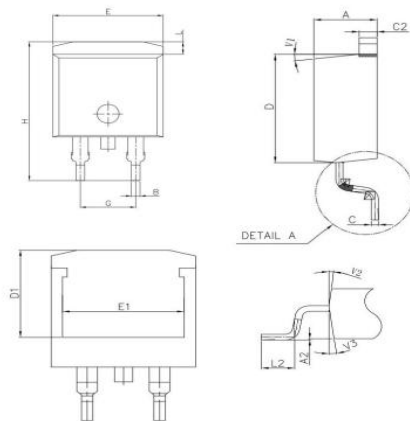
**Package Outline**



DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	4.24		4.70
A1	2.20		3.00
b	0.70		0.95
b1	1.14		1.70
C	0.40		0.60
C1	1.15		1.40
D	28.00		29.80
D1	8.80		9.90
E	9.70		10.50
L1			3.80
L2	6.25		6.90
L3	2.40		3.00
c		2.54 BSC	

**TO-263-3L Package Information (All units in mm)**

**Package Outline**



SYMBOL	DIMENSIONS		
	MIN	NOM	MAX
A	4.3	4.55	4.7
A2	0		0.25
B	0.75	0.8	0.85
C	0.38	0.46	0.55
C2	1.25	1.3	1.35
D	8.9	9.3	9.6
D1	7.4	7.65	7.9
E	9.9	10.05	10.21
E1	8.3	8.6	8.9
G	5.03	5.08	5.13
H	14.7	15	15.8
L2	2.2	2.35	2.5

**Recommended Footprint**

